

COPPER ALLOY BONDING WIRE

ABSTRACT

[Problem to be Solved] The present invention has been made for solving a problem of bending of the tip of a copper alloy bonding wire into a J-like shape when the bonding wire is cut by pulling up after wedge bonding. It is an object to provide a copper alloy bonding wire of which the cut end does not protrude from a cross section of the bonding wire by restricting the crystal grain size and forming a non-oriented state.

[Solution] The copper alloy bonding wire of the present invention is characterized in that a cross section of the bonding wire contains 50 to 250 crystal grains, the crystal grains have a maximum grain size of one third or less of the diameter of the bonding wire, and every specific orientation, including a $\langle 100 \rangle$ orientation, is 40% or less to give a non-oriented state.

[Selected Drawing] Fig. 1